



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
Q1	30V	$16m\Omega @ V_{GS} = 10V$	8.2A
QI	307	$20m\Omega @ V_{GS} = 4.5V$	7.3A
Q2	-30V	28mΩ @ V _{GS} = -10V	-6.2A
QZ	-307	38mΩ @ V _{GS} = -4.5V	-5.2A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- **DC-DC Converters**
- **Power Management Functions**
- Backlighting

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

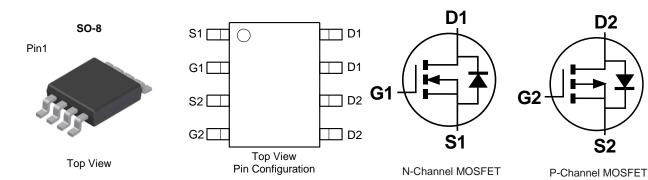
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 3

D2

S2

Weight: 0.074 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMC3016LSD-13	SO-8	2,500/Tape & Reel

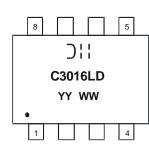
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



) | | = Manufacturer's Marking C3016LD = Product Type Marking Code YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 15 = 2015) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value Q1	Value Q2	Units		
Drain-Source Voltage	V _{DSS}	30	-30	V		
Gate-Source Voltage			V _{GSS}	±20	±20	V
	Steady	T _A = +25°C	I _D	8.2	-6.2	А
Continuous Drain Current (Noto 6) Ves - 10V	State	$T_{A} = +70^{\circ}C$	U	6.5	-5.0	
Continuous Drain Current (Note 6) $V_{GS} = 10V$	t<10s	T _A = +25°C	ID	10.5	-8.0	А
		T _A = +70°C		8.4	-6.4	
Maximum Body Diode Forward Current (Note 6)			I _S	2.5	-2.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = '	I _{DM}	80	-40	А		
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	22	-22	A
Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	25	25	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Units		
Tatal Dower Dissinction (Note 5)	T _A = +25°C	D	1.2	W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.8	vv	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	102	°C/W	
mermai Resistance, Junction to Amblent (Note 5)	t<10s	$R_{\theta JA}$	62	C/VV	
Total Power Dissipation (Note 6)	T _A = +25°C	D	1.6	W	
	T _A = +70°C	PD	1.0		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	78	°C/W	
memai Resistance, Junction to Amblent (Note 6)	t<10s	$R_{\theta JA}$	47		
Thermal Resistance, Junction to Case (Note 6)	R _{ejc}	12			
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

Electrical Characteristics (N-Channel Q1) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_		V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	—	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)	·					-
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	Passar	—	12	16	mΩ	$V_{GS} = 10V, I_D = 12A$
	R _{DS(ON)}	—	15	20	11152	$V_{GS} = 4.5V, I_D = 10A$
Diode Forward Voltage	V _{SD}	—	0.7	1.0	V	$V_{GS} = 0V, I_S = 1A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{ISS}	—	1,415	—		V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{OSS}	_	119		pF	
Reverse Transfer Capacitance	C _{RSS}	—	82	_		
Gate Resistance	R _G	—	2.6	3.2	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = 4.5V)	Q _G	—	11.3	_		V _{DS} = 15V, I _D = 12A
Total Gate Charge (V _{GS} = 10V)	Q _G	—	25.1	_	nC	
Gate-Source Charge	Q _{GS}	_	3.5			
Gate-Drain Charge	Q _{GD}	_	3.6			
Turn-On Delay Time	t _{D(ON)}	—	4.8	_		
Turn-On Rise Time	t _R	—	16.5		-	$V_{DD} = 15V, V_{GS} = 10V,$
Turn-Off Delay Time	t _{D(OFF)}	_	26.1	_	ns	$R_L = 1.25\Omega, R_G = 3\Omega,$
Turn-Off Fall Time	t _F	—	5.6		1	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

7. UIS in production with L = 0.1mH, starting T_A = +25°C.

8. Short duration pulse test used to minimize self-heating effect.

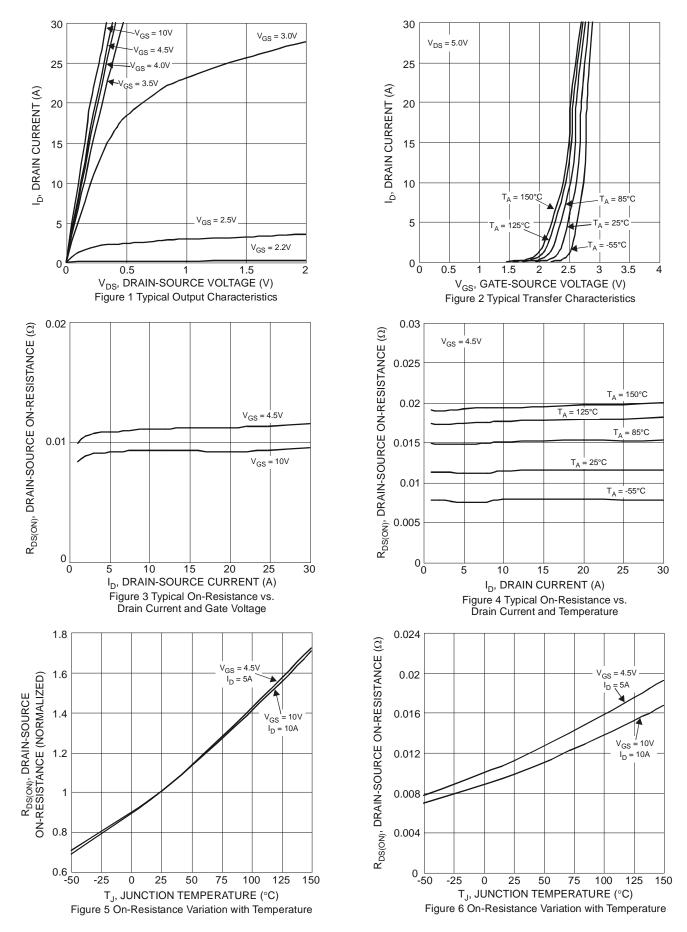
9. Guaranteed by design. Not subject to product testing.



Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	<u>.</u>					
Drain-Source Breakdown Voltage	BV _{DSS}	-30	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μA	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)		•		•		·
Gate Threshold Voltage	V _{GS(th)}	-1.0		-3.0	V	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$
Static Drain-Source On-Resistance	D		21	28	mΩ	V _{GS} = -10V, I _D = -7A
Static Drain-Source On-Resistance	R _{DS} (ON)		30	38	11122	$V_{GS} = -4.5V, I_D = -6.2A$
Diode Forward Voltage	V _{SD}		-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -2.1A$
DYNAMIC CHARACTERISTICS (Note 9)		•		•		·
Input Capacitance	CISS	—	1,241	—		V _{DS} = -15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{OSS}	—	147	—	pF	
Reverse Transfer Capacitance	C _{RSS}	—	110	—		
Gate Resistance	R _G	—	15	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = -4.5V)	Q _G	_	10.9	_		Vds = -15V, Id = -7A
Total Gate Charge (V _{GS} = -10V)	Q _G		22	_	nC	
Gate-Source Charge	Q _{GS}		3.5	_	nc	
Gate-Drain Charge	Q _{GD}		4.7	_		
Turn-On Delay Time	t _{D(ON)}	_	9.7	_		
Turn-On Rise Time	t _R	—	17.1	_	20	VDS = -15V, ID = -7A
Turn-Off Delay Time	t _{D(OFF)}	—	60.5	_	ns	$V_{GS} = -10V, R_{G} = 6\Omega$
Turn-Off Fall Time	t _F	_	40.4	_		

Electrical Characteristics (Continued) (P-Channel Q2) (@T_A = +25°C, unless otherwise specified.)

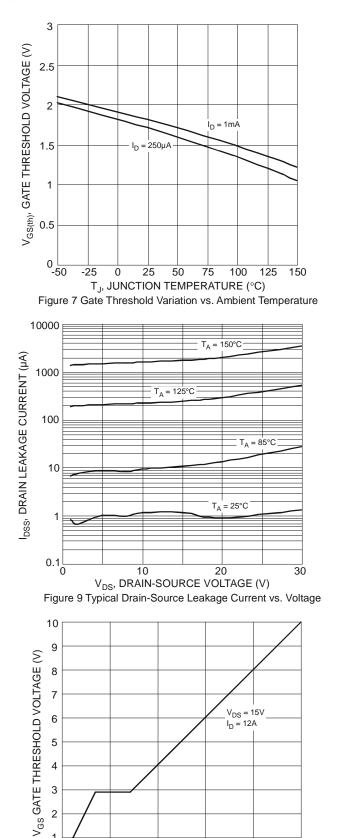


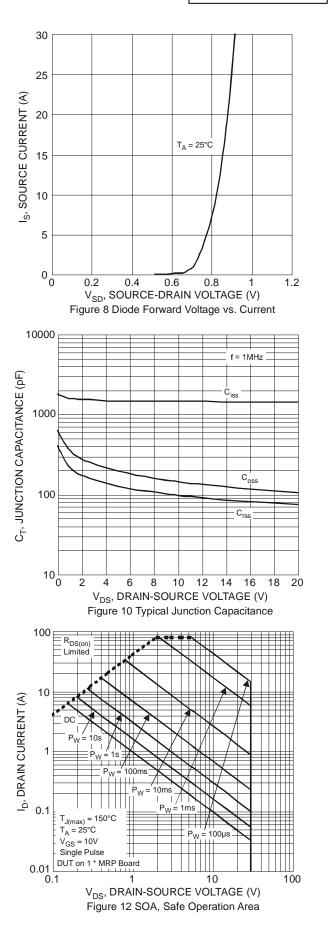




DMC3016LSD







5

10

15

Q_q, TOTAL GATE CHARGE (nC)

Figure 11 Gate Charge

20

25

4 3

2

1

0 <u>k</u>



DMC3016LSD

4

T_A = 150°C

 $T_A = 85^{\circ}C$

 $T_A = -55^{\circ}C$

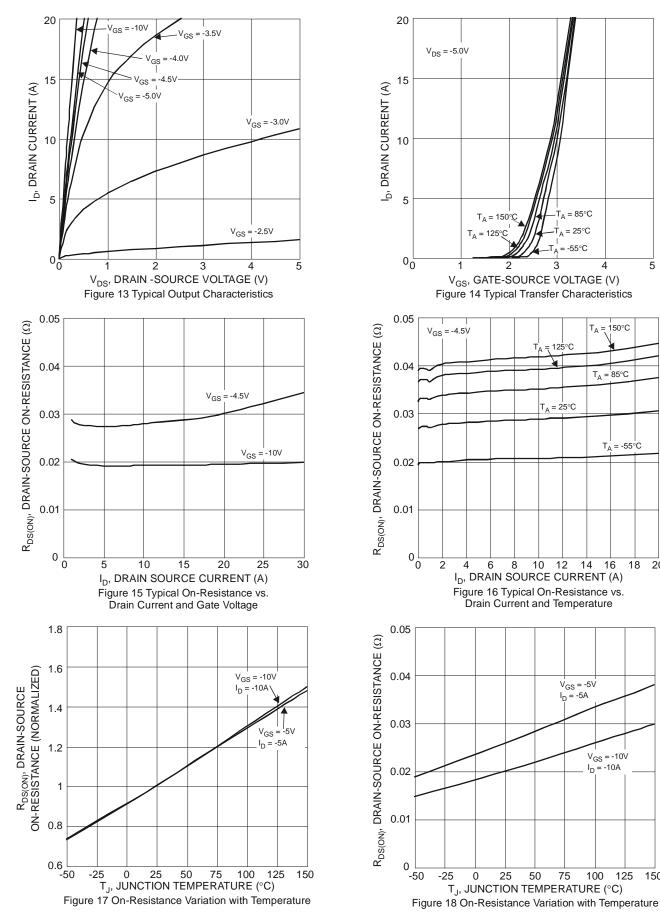
18 20

V_{GS} = -10V I_D = -10A

100

125

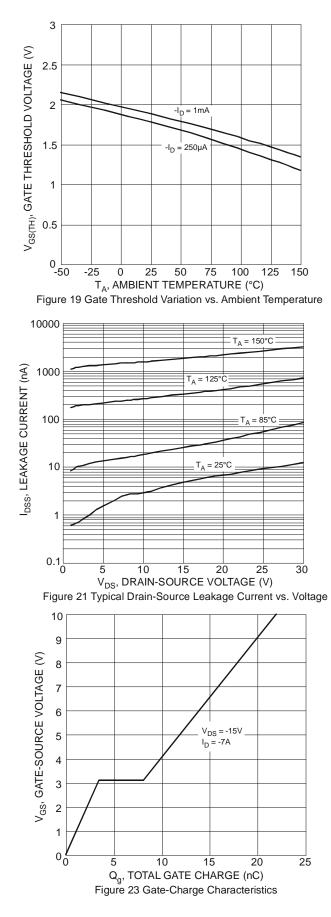
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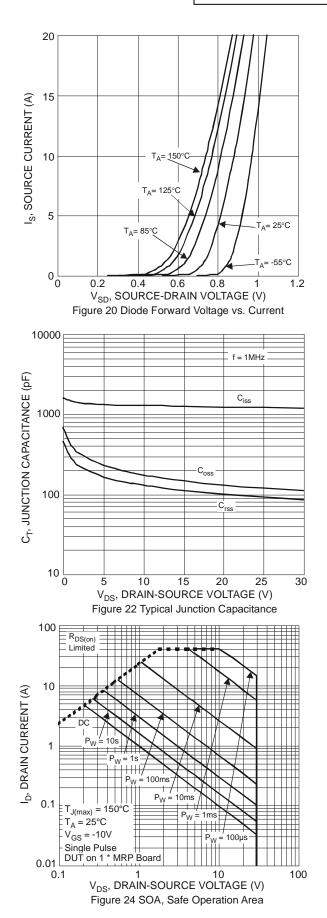


DMC3016LSD Document Number: DS36935 Rev. 4 - 2 150



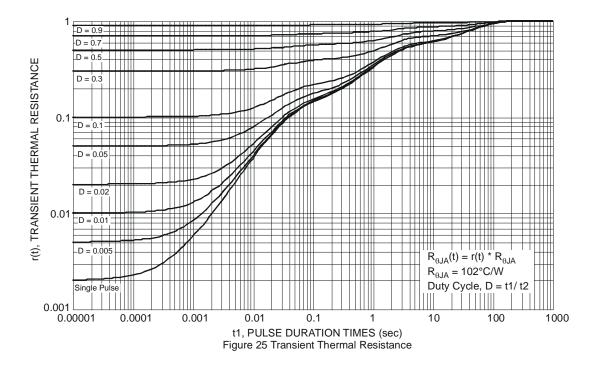
DMC3016LSD





DMC3016LSD Document Number: DS36935 Rev. 4 - 2

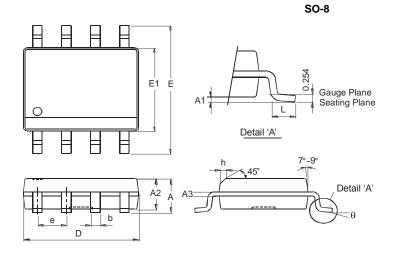






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

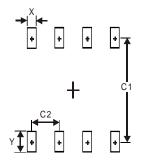


	SO-8						
Dim	Min	Max					
Α	_	1.75					
A1	0.10	0.20					
A2	1.30	1.50					
A3	0.15	0.25					
b	0.3	0.5					
D	4.85	4.95					
Е	5.90	6.10					
E1	3.85	3.95					
е	1.27	Тур					
h	_	0.35					
L	0.62	0.82					
θ	0°	8°					
All Di	All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

SO-8



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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